



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-03-09
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	H507*AU12CDB	A	ZY1A	2015-04-21
Amount	UoM	Unit type	ST ECOPACK Grade	
76.50	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ting is used or other bulk terminat	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85x3.9x1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC; MDF valid for AIS2120SACUTR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound

ELV exemption number	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	false
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Exemption Id.	Description
10a	Electrical and electronic components which contain lead in a glass or ceramic, in a glass or ceramic matrix compound, in a glass-ceramic

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead monoxide (lead oxide)	1000 ppm	0.218		2850

Material Composition Declaration						Mfr Item Name	HS07*AU12CDB					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	10.490	mg	supplier	die	Silicon (Si)	7440-21-3		9.649	mg	919828	126131
die (s)				supplier	metallisation	Aluminium (Al)	7429-90-5		0.072	mg	6864	941
die (s)				supplier	metallisation	Gold (Au)	7440-57-5		0.087	mg	8294	1137
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.016	mg	1525	209
die (s)				supplier	passivation	Silicon Oxide	7631-86-9		0.325	mg	30982	4248
die (s)				SVHC	passivation	Lead Oxide	1317-36-8	7c-I-Electrical and e	0.218	mg	20782	2850
die (s)				SVHC	passivation	Boron Trioxide	1303-86-2		0.024	mg	2288	314
die (s)				supplier	passivation	Silicon Oxide	7631-86-9		0.034	mg	3241	444
die (s)				supplier	passivation	Aluminium oxide	1344-28-1		0.034	mg	3241	444
die (s)				supplier	passivation	Butyl Carbitol Acetate	124-17-4		0.017	mg	1621	222
die (s)				supplier	passivation	Ethyl cellulose	9004-57-3		0.007	mg	667	92
die (s)				supplier	passivation	Terpineol	8000-41-7		0.007	mg	667	92
Leadframe	Copper & its alloys	23.861	mg	supplier	alloy	Copper (Cu)	7440-50-8		22.982	mg	963162	300418
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.540	mg	22631	7059
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.033	mg	1383	431
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.028	mg	1173	366
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.258	mg	10813	3373
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.011	mg	461	144
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.009	mg	377	118
Die attach	Other inorganic materials	0.080	mg	supplier	glue or tape (choose)	Novolac Epoxy resin	29690-82-2		0.011	mg	137500	144
Die attach				supplier	glue or tape	Phenolic resin	Proprietary		0.011	mg	137500	144
Die attach				supplier	glue or tape	amorphous silica	60676-86-0		0.002	mg	25000	26
Die attach				supplier	glue or tape	Acrylic copolymer resin	28262-63-7		0.056	mg	700000	732
Bonding wire	Other inorganic materials	0.315	mg	supplier	wire	Gold (Au)	7440-57-5		0.312	mg	990476	4078
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.003	mg	9524	39
encapsulation	Other inorganic materials	41.139	mg	supplier	mold compound	Epoxy Resin	Proprietary		3.086	mg	75014	40340
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		2.057	mg	50001	26889
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		35.625	mg	865967	465686
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.206	mg	5007	2693
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.165	mg	4011	2157
connections coating	Solder	0.615	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.615	mg	1000000	8039